upplier Information ompany name* Company unique ID	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date*	752-21.1											als and Mf	g Informat	ion		
Semilar Contact Name Title - Contact Phone - Contact Phone - Contact Email - Contact Ema	upplier Informa	ntion														
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Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards @onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Ty MC12093DG BBG LO PWR PRESCLR 2/4/8 2023-06-08 PH1 72.0 mg Each Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 Tomments Weight* UOM Unit Ty Max Time at Peak Temperature Number of Reflow Cycles seconds 3	Product-Env-Stewar	ds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	uthorized Represen	tative*	Title - Representative			I	Phone - Representative*			Email - Representative*						
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or more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	led				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybrominated Biphenyls (Pl	aterial for Cadmium and quantity limit of 0.1% by BB), Polybrominated Diphenyl Ethers (PBDE), an						
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the company that the company tha	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose al applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the				
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.7898	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		35.8799	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.19	mg	Supplier	Gold (Au)	7440-57-5		0.19	mg